## BYV26B

# SINTERED GLASS JUNCTION FAST AVALANCHE RECTIFIER

VOLTAGE: 400V CURRENT: 1.0A



### **FEATURE**

Glass passivated
High maximum operating temperature
Low leakage current
Excellent stability
Guaranteed avalanche energy absorption capability

## **MECHANICAL DATA**

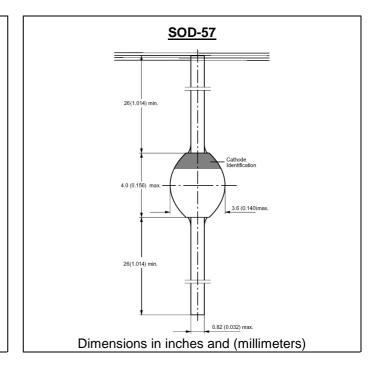
Case: SOD-57 sintered glass case

Terminal: Plated axial leads solderable per

MIL-STD 202E, method 208C

Polarity: color band denotes cathode end

Mounting position: any



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

|  |                   | SYMBOL              | BYV26B      | units |
|--|-------------------|---------------------|-------------|-------|
| Maximum Recurrent Peak Reverse Voltage                                 |                   | $V_{RRM}$           | 400         | V     |
| Maximum RMS Voltage  |                   | $V_{RMS}$           | 280         | V     |
| Maximum DC blocking Voltage  |                   | $V_{DC}$            | 400         | V     |
| Reverse avalanche breakdown voltage<br>at IR = 0.1 mA                  |                   | V <sub>(BR)R</sub>  | 500min      | V     |
| Maximum Average Forward Rectified Current 3/8"lead length at Ttp =85°C |                   | I <sub>FAV</sub>    | 1.0         | А     |
| Non-repetitive Peak Forward Current at t=10ms half sine wave           |                   | I <sub>FSM</sub>    | 30          | А     |
| Maximum Forward Voltage at rated Forward Current                       |                   | V <sub>F</sub>      | 2.5         | V     |
| Non-repetitive peak reverse avalanche energy (Note 1)                  |                   | E <sub>RSM</sub>    | 10          | mJ    |
| Maximum DC Reverse Current   | Ta =25°C          | I_                  | 5.0         | μΑ    |
| at rated DC blocking voltage   | Ta =165° <b>C</b> | I <sub>R</sub>      | 150.0       | μΑ    |
| Maximum Reverse Recovery Time  | (Note 2)          | Trr                 | 30          | nS    |
| Diode Capacitance  | (Note 3)          | C <sub>d</sub>      | 45          | pF    |
| Typical Thermal Resistance   | (Note 4)          | R <sub>th(ja)</sub> | 100         | °C M  |
| Storage and Operating Junction Temperature                             |                   | Tstg, Tj            | -65 to +175 | °C    |

#### Note:

- 1. R=400mA; Tj=Tjmax prior to surge; inductive load switched off
- 2. Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
- 3. Measured at 1.0 MHz and applied reverse voltage of 0Vdc
- 4. Device mounted on an epoxy-glass printed-circuit board, 1.5mm thick; thickness of Cu-layer ≥40 μ m

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#### **RATINGS AND CHARACTERISTIC CURVES BYV26B**

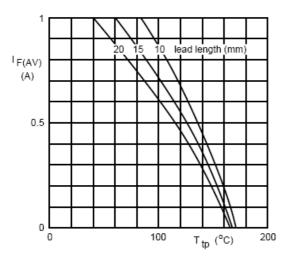


Fig.1 Maximum average forward current as a function of tie-point temperature (including losses due to reverse leakage).

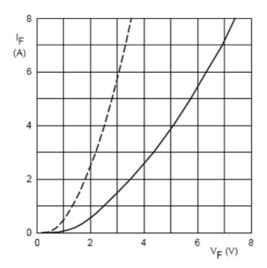


Fig. 3 Forward current as a function of forward voltage; maximum values.

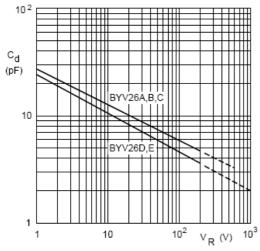


Fig. 5 Diode capacitance as a function of reverse voltage, typical values.

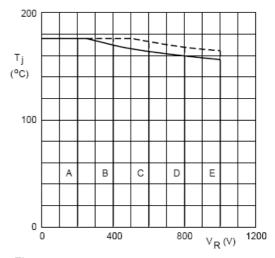


Fig. 2 Maximum permissible junction temperature as a function of reverse voltage.

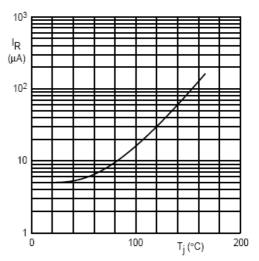


Fig.4 Reverse current as a function of junction temperature; maximum values.

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